

MODEL ATM-8100S

Automatic Wafer Mounter

Outline

The ideal system for mounting wafers to dicing frames, before the dicing process.

Features

- Applicable 150 μ m thickness, 5mm warped wafer.
- Wafer warp is corrected by vacuum holding in vacuum chamber.
- Adjustable for use with a wide range of tapes by the Tape tension memory function.
- Carrier station memory function
- Option: ID reader, Barcode labeller

In line system for pairing with TEAM-200



Specification		ATM-8100S
Throughput		80 wafers/h (Depend on data setting)
Wafer Size		6 inch、 8 inch
Frame Size		2 6 1、 2 8 1
Tape Width		6 inch : W 230mm 8 inch : W 300mm
Utilities	Power	AC200V Single phase 50 / 60Hz 3.0KVA
	Air	Pressure 0.5Mpa 300NI/min
	Vacuum source	Using venturi valve
Dimensions		D 1,200 × W 1,646 × H 1,800mm
Weight		850kg

System appearance and specifications are subject to change without prior notice from the supplier.

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